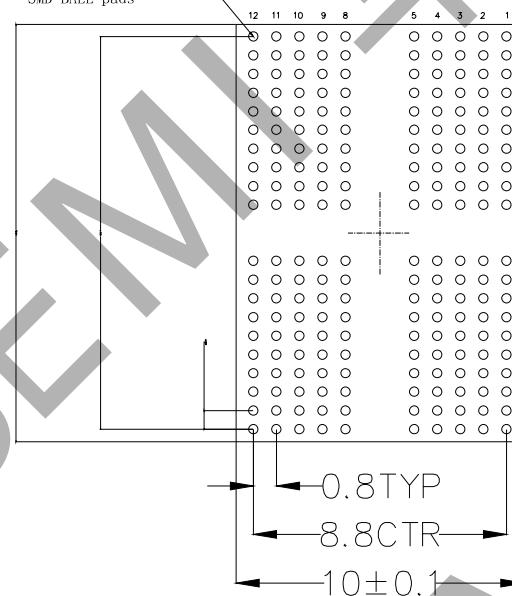


RoSH

200X $\Phi 0.35 \pm 0.05$
dimensions apply
to solder balls
postreflow on $\Phi 0.28$
SMD BALL pads



SEATING plane

0.08 A

POD
(SCALE = 6:1)

QUALITY SPECIFICATION	
ITEM	SPEC. (mm)
Mold Thickness	0.6500
Substrate Thickness	0.1800
Ball Size	0.3500

NOTES: 1. All dimensions are in millimeters.
2. Solder ball composition: SAC302 with NiAu pads (Sn-3Ag-0.2Cu).

产品图

履历

序号	内容	日期
1	新发行	2025.11.4

确认签字回传

SIGNATURE AREA	DESIGN		
	CHECK		
	DESIGN APPROVE		
	PROCESS		
	STAND.		
	APPROVE		

FORMAT CODE: A